

12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN#20200408000.1 Qualify TI Chengdu as an additional Assembly site for select devices Change Notification / Sample Request

Date: May 08, 2020 **To:** Flextronics PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

We request you acknowledge receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance of the change. If you require samples or additional data to support your evaluation, please request within 30 days.

The proposed first ship date is indicated on page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Team (<u>PCN ww admin team@list.ti.com</u>). For sample requests or sample related questions, contact your field sales representative.

Sincerely,

PCN Team SC Business Services

20200408000 Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE

TPS2556DRBR TPS2556DRBR TPS2556DRBT **CUSTOMER PART NUMBER**

CISH-15-13339-01 VRJH-11146-EE

Technical details of this Product Change follow on the next page(s).

PCN Number: 20200408000.1			<u> </u>	PCN	<u> </u>	t o.	May 8 2020		
			000.1			Da	ite:	May 8, 2020	
Title: Qualify TI Chengdu as an additional Assembly site for select devices									
Customer Contact:	PCN Mai	<u>nager</u>	Dept:	Quality Ser					
Proposed 1 st Ship Date: At		ug 8, 202	ug 8, 2020		Estimated Sample Availability:			Provided upon Request	
Change Type:									
Assembly Site		Design					fer Bump Site		
Assembly Process		Data She			Ц	Wafer Bump Material			
Assembly Materials			Part numb			Ц.	Wafer Bump Process		
Mechanical Specific		Test Site			Ц.	Wafer Fab Site Wafer Fab Materials			
Packing/Shipping/L		Test Process			\vdash		Vafer Fab Materials Vafer Fab Process		
			PCN Details				wai	er rab Process	
Description of Change	e:		PCN De	cans					
Texas Instruments is pleased to announce the qualification of TI Chengdu as additional Assembly Site for Select Devices listed in the "Product Affected" Section. Material differences are as follows. Material Differences:									
		TI	Clark	TI Ch	nengo	du			
Mount compound	Mount compound)7768	420	4207123				
Mold compound		420	08625	422	4222198				
Reason for Change:									
Continuity of Supply									
Anticipated impact on	Fit, F	orm, Fun	ction, Qu	ality or Rel	iabili	ity	(posi	tive / negative):	
None None									
Anticipated impact or	Mate	rial Decla	aration						
Material Declaration produced			Material Declarations or Product Content reports are driven from production data and will be available following the production release. Upon production release the revised reports can be obtained from the TI Eco-Info website. There is no impact to the material meeting current regulatory compliance requirements with this PCN change.						
Changes to product identification resulting from this PCN:									
Assembly Site TI Clark Assembly Site Origin (22L) ASO:OAB									
TI Clark Assembly Site Origin (22L) ASO:QAB TI Chengdu Assembly Site Origin (22L) ASO: CDA									
Sample product shipping label (not actual product label)									
TEXAS INSTRUMENTS MADE IN: Malaysia 2DC: 20: MSL '2 /260C/1 YEAR SEAL DT MSL 1 /235C/UNLIM 03/29/04 OPT: ITEM: BL: 5A (L) TO: 1750 (1P) \$N74L\$07N\$R (Q) 2000 (D) 0336 (31T) LOT: 3959047MLA (4W) TKY(1T) 7523483S12 (P) (2P) REV: (V) 0033317 (20L) CSO: SHE (21L) CCO: USA (22L) ASO: MLA (23L) ACO: MYS									
Product Affected									
TPS2556DRBR TPS2556DRBT									

Qualification Report

Approve Date 06-Apr-2020

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Туре	Test Name / Condition	Duration	Qual Device: TPS2556DRBR	QBS Product Reference: TPS2556DRB	QBS Package Reference: BQ25895RTWR	QBS Package Reference: LP5922	QBS Package Reference: TPS3850G09DRC
AC	Autoclave 121C	96 Hours	-	-	-	-	3/240/0
HAST	Biased HAST, 130C/85%RH	96 Hours	-	-	-	-	3/231/0
HTOL	Life Test, 125C	1000/hrs @125C	-	-	-	1/80/0	-
HTSL	High Temp Storage Bake 150C	1000/hrs @150C	-	-	-	3/239/0	-
HTSL	High Temp Storage Bake 170C	420 Hours	1	-	3/231/0	-	3/231/0
LU	Latch-up	(per JESD78)	-	-	-	-	1/6/0
MQ	Manufacturability (Assembly)	(Approved by AT site)	3/Pass	1/Pass	3/Pass	3/3/0	1/Pass
TC	Temperature Cycle, -65/150C	(MSL 2 / 260C)	3/231/0	-	3/231/0	3/231/0	3/231/0
UHAST	Unbiased HAST 130C/85%RH	96 Hours	-	-	3/231/0	3/239/0	-

- QBS: Qual By Similarity
- Qual Device TPS2556DRBR is qualified at LEVEL2-260CG
- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles Quality and Environmental data is available at TI's external Web site: http://www.ti.com/Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

For questions regarding this notice, e-mails can be sent to the contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
WW PCN Team	PCN www admin team@list.ti.com

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